

This listing of claims will replace all prior versions, and listing of claims in the application.

In the Claims

Claims 1-6 (cancelled)

Claim 7 (currently amended): A process of manufacturing a chip-type LED ~~according to claim 1~~ comprising the steps of:

- accommodating a LED element in a tubular vessel;
- closely adhering the vessel to an adhesive tape to seal an upper opening of the vessel with the adhesive tape;
- adding dropwise a light-transmissive resin through a lower opening of the vessel; and
- peeling off the adhesive tape from the vessel.

Claim 8 (currently amended): A process of manufacturing a chip-type LED ~~according to claim 3~~ comprising the steps of:

- inserting a first lead frame and a second lead frame into a tubular vessel;
- mounting a LED element on the first lead frame, to electrically connect the LED element to the first and second lead frames;
- closely adhering the vessel to an adhesive tape to seal an upper opening of the vessel with the adhesive tape;
- adding dropwise a light-transmissive resin containing a fluorescent material through a lower opening of the vessel to form a fluorescent layer in a neighborhood of the upper opening,
- adding dropwise a light-transmissive resin through the lower opening of the vessel; and
- peeling off the adhesive tape from the vessel.

Claim 9 (currently amended): A process of manufacturing a chip-type LED ~~according to claim 5~~ comprising the steps of:

- inserting a first lead frame and a second lead frame into a tubular vessel;

placing a pot-shaped cup on the first lead frame, accommodating a LED element for emitting bluish-purple light in the cup to electrically connect the LED element to the first and second lead frames;

closely adhering the vessel to an adhesive tape to seal an upper opening of the vessel with the adhesive tape;

adding dropwise a light-transmissive resin containing a fluorescent material through a lower opening of the vessel to form the fluorescent layer in a neighborhood of the upper opening; and

peeling off the adhesive tape from the vessel.

Claim 10 (currently amended): A process of manufacturing a chip-type LED ~~according to claim 6~~ comprising the steps of:

forming a first wiring trace and a second wiring trace on a rear surface of an insulating substrate having a bore penetrating from a front surface to the rear surface so that the first and second wiring traces are partially extend into a rear opening of the bore;

mounting a LED element on the first wiring trace to electrically connect the LED element to the first and second wiring traces;

forming an insulating film having a hole leading into the bore to cover the first and second wiring traces and the rear opening;

closely adhering the insulating substrate to an adhesive tape to seal a front opening of the bore with the adhesive tape;

adding dropwise a light-transmissive resin through the hole of the insulating film to form a light-transmissive member covering the LED element; and

peeling off the adhesive tape from the insulating substrate.

Claim 11 (new): A process of manufacturing a chip-type LED according to claim 7,

wherein the vessel has an inner wall extending from the upper opening to the lower opening through an intermediate position,

the LED element is positioned at the intermediate position such that the LED element emits light toward the upper opening, and

the inner wall has a first diminishing conical taper from the upper opening to the intermediate position and a second diminishing conical taper from the lower opening to the intermediate position.

Claim 12 (new): A process of manufacturing a chip-type LED according to claim 7,

wherein the step of adding dropwise the light-transmissive resin includes a step of adding dropwise the light-transmissive resin through the lower opening of the vessel such that the vessel is filled with the light-transmissive resin from the upper opening to the lower opening.